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(71)Applicant : MITSUBISHI PLASTICS IND LTD

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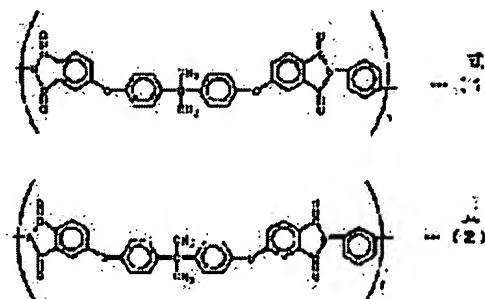
(72)Inventor : TANIGUCHI KOICHIRO

(54) HEAT-RESISTANT FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a heat-resistant film superior in the use for electronic parts, which has good weldability at a low temperature ($\leq 260^{\circ}\text{C}$), and good in balance of solder resistance and end-shearing resistance after PTC(pressure cooker test).

SOLUTION: This heat-resistant film is characterized by comprising a mixture film in which a filler is mixed within the range of 5-50 parts of the filler to 100 pts.wt. of a mixed resin consisting of at least three components of a polyether-imide resin (A-1) which has repeating structural unit shown in structural formula (1), a polyether-imide resin (A-2) having a repeating structural unit shown by structural formula (2), and a polyaryl ketone resin (B), and the mixing ratio by weight of each component is $[(A-1)+(A-2)]/(B)=70-30/30-70$, and $(A-1)/(A-2)=70-30/30-70$.



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DETAILED DESCRIPTION

[Detailed Description of the Invention]

[0001]

[Field of the Invention] This invention relates to a heat-resistant film suitable as a member for electronics etc. In a detail, the thermal melting arrival nature in low temperature (≤ 260 degree C) is still better, and it is related with the heat-resistant film excellent in the balance of the solder thermal resistance after PCT (pressure cooker trial) processing, and a tear-strength-propagating value.

[0002]

[Description of the Prior Art] Since it excels in thermal resistance, fire retardancy, hydrolysis-proof nature, chemical resistance, etc., many crystalline poly aryl ketone resin represented by polyether ether ketone resin is adopted centering on aircraft components, and the electrical and electric equipment and electronic parts. However, heat-resistant amelioration examination has been variously performed from poly aryl ketone resin having a glass transition temperature of the top where a raw material price is very expensive, and resin itself comparatively as low as about about 140-170 degrees C. As a system which shows good compatibility also in it, the blend with amorphous polyetherimide resin has attracted attention. this invention persons proposed the printed-circuit board which used the above-mentioned mixed constituent by JP,2000-38464,A, JP,2000-200950,A, etc., and its manufacture approach.

[0003]

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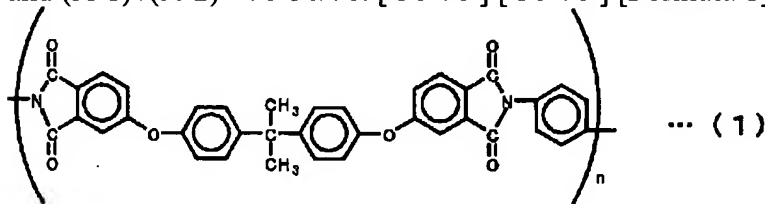
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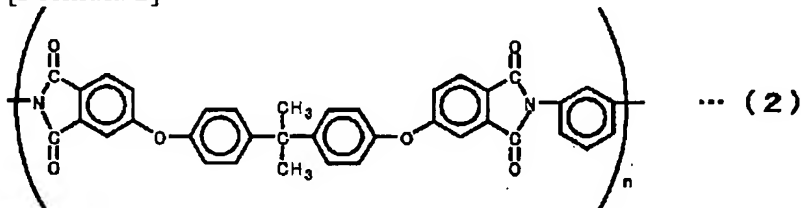
 CLAIMS

[Claim(s)]

[Claim 1] The repeat unit of the following structure expression (1) As opposed to the resin constituent 100 weight section which the polyetherimide resin (A-1) which it has, the polyetherimide resin (A-2) which has the repeat unit of the following structure expression (2), and crystal fusion peak temperature become from at least 3 components of the poly aryl ketone resin (B) which is 260 degrees C or more The heat-resistant film characterized by being the film which mixed the filler in the range of 5 - 50 weight section, and the mixed weight ratios of each component being $\{(A-1) + (A-2)\} / (B) = 70-30/70$, and $(A-1) / (A-2) = 70-30/70$. [30-70] [30-70] [Formula 1]



[Formula 2]



 [Translation done.]